

WHAT IS CLAIMED IS:

1. A position detection method for detecting the position of marks, comprising the following steps:

a step for detecting first information relating to the position of said mark by detecting light from said mark under first measurement conditions;

a step for detecting second information relating to the position of said mark by detecting light from said mark under second measurement conditions which differ from said first measurement conditions; and

a step for detecting the position of said mark based on said first and second information.

2. A position detection method according to Claim 1, wherein said first and second information is detected in said step for detecting first information and said step for detecting second information by receiving light from said mark by light receiving means via an optical system;

and wherein the focus state of said mark differs between that received by said light receiving means under said first measurement conditions and that received under said second measurement conditions.

3. A position detection method according to Claim 1,

wherein said first and second information is detected in said step for detecting first information and said step for detecting second information by detecting light from said mark via an optical system;

and wherein the NA of said optical system differs between that of said first measurement conditions and that of said second measurement conditions.

4. A position detection method according to Claim 1, wherein said first and second information is detected in said step for detecting first information and said step for detecting second information by detecting light irradiated onto said mark via illumination system;

and wherein the coherency of said illumination system differs between that of said first measurement conditions and that of said second measurement conditions.

5. A position detection method according to Claim 1, wherein at least one of the polarization direction and wavelength of the light from said mark differs between that of said first measurement conditions and that of said second measurement conditions.

6. A position detection method according to Claim 1, wherein said first information and said second information

is positional information of the measurement direction of said mark;

and wherein the position of said mark is detected in said step for detecting the position of said mark, based on the difference in position information of said first information and said second information.

7. An exposure apparatus, comprising:

position detecting means for detecting a position of a mark on a surface of a workpiece to be exposed, said position detecting means including

means for detecting first information relating to the position of said mark by detecting light from said mark under first measurement conditions,

means for detecting second information relating to the position of said mark by detecting light from said mark under second measurement conditions different from said first measurement conditions, and

means for detecting the position of said mark based on said first and second information; and

exposure means for aligning the workpiece by use of positional information related to a position of the mark detected by said position detecting means, and subjecting the workpiece to pattern exposure.

8. A device manufacturing method, comprising the steps of:

a position detecting step for detecting a position of a mark on a surface of a workpiece to be exposed, comprising the substeps of:

a substep for detecting first information relating to the position of said mark by detecting light from said mark under first measurement conditions,

a substep for detecting second information relating to the position of said mark by detecting light from said mark under second measurement conditions different from said first measurement conditions, and

a substep for detecting the position of said mark based on said first and second information;

a pattern exposure step for aligning the workpiece by use of position information related to a position of the mark detected by said position detecting means, and subjecting the workpiece to pattern exposure; and

a developing step for developing the workpiece having been exposed in said pattern exposure step, whereby a device can be produced from the developed workpiece.